



PRELIMINARY

ISD1700 Series

Design Guide



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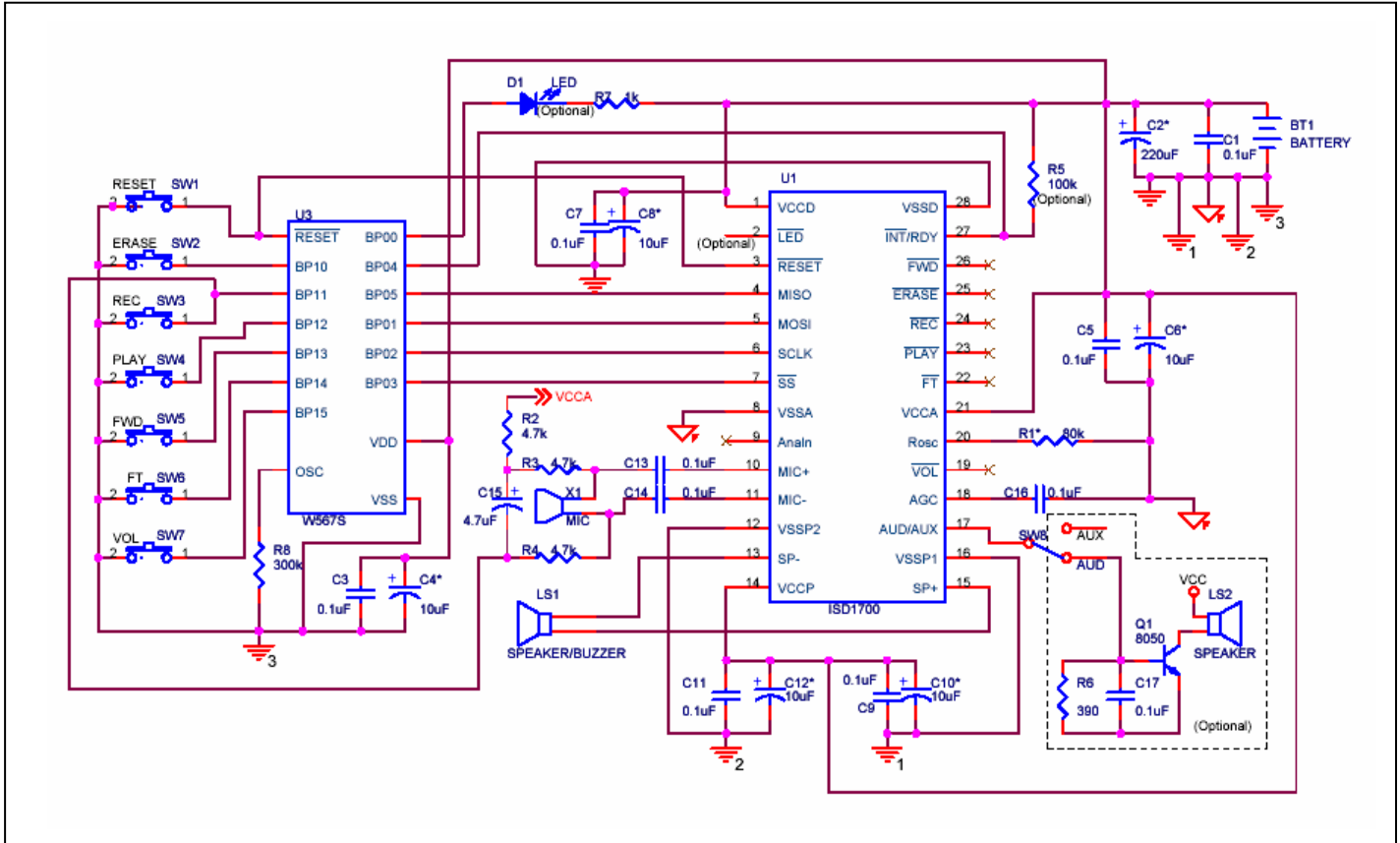
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Example #4: Connecting the ISD1700 with PowerSpeech W567



15.1 GOOD AUDIO DESIGN PRACTICES

To ensure the highest quality of voice reproduction, it is important to follow good audio design practices in layout and power supply decoupling. See recommendations from below links or other Application Notes in our websites.

Design Considerations for ISD1700 Family

AN-CC1002 Design Considerations for ISD1700 Family

Good Audio Design Practices

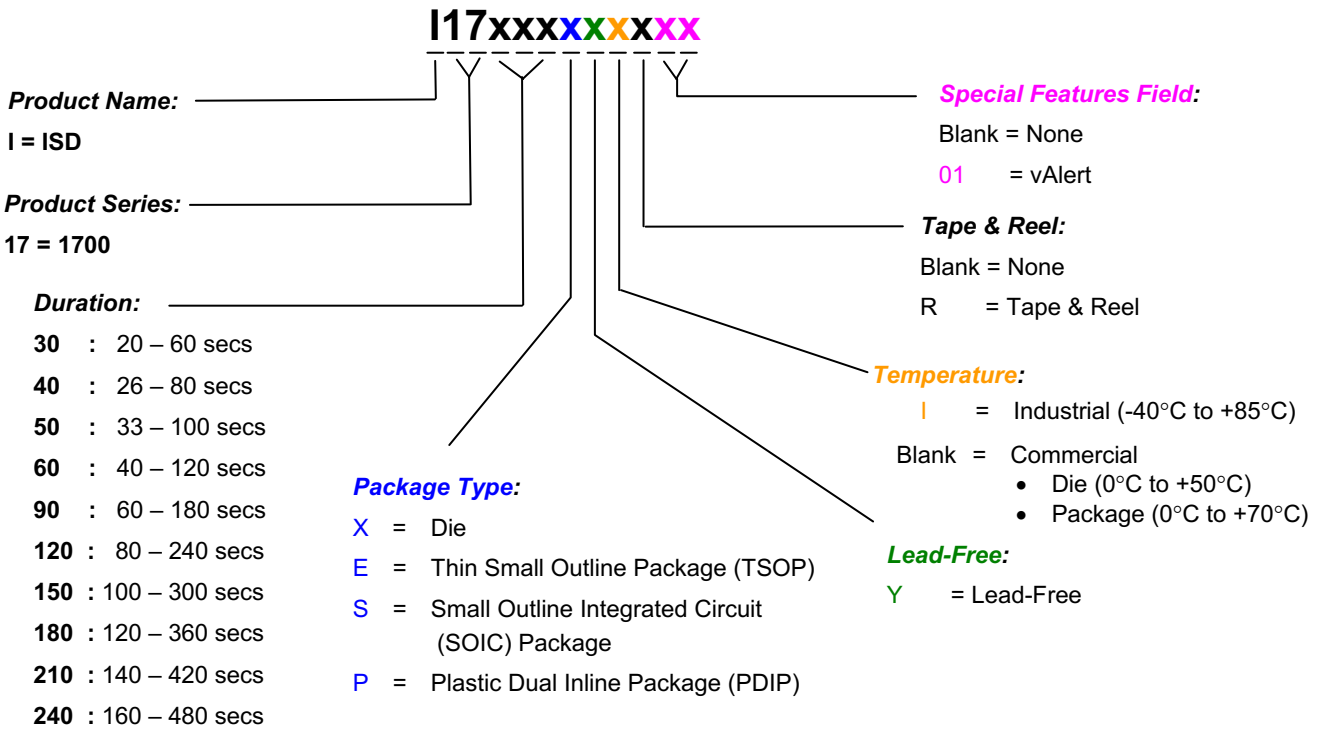
http://www.winbond-usa.com/products/isd_products/chipcorder/applicationinfo/apin11.pdf

Single-Chip Board Layout Diagrams

http://www.winbond-usa.com/products/isd_products/chipcorder/applicationinfo/apin12.pdf

16 ORDERING INFORMATION

Product Number Descriptor Key



When ordering ISD1700 devices, please refer to the above ordering scheme. Contact the local Winbond Sales Representatives for any questions and the availability.

For the latest product information, please contact the Winbond Sales/Rep or access Winbond's worldwide web site at <http://www.winbond-usa.com>

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17 VERSION HISTORY

VERSION	DATE	DESCRIPTION
0	October 2006	Initial version
1	January 2007	Revise Rosc resistor value and standby current parameter Update read status command: description & figure

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